

MacuSpec™ HT 300

Electrolytic Copper Metallization

The New Standard in High Throw DC: Pulse-like Performance in Your Existing DC Plating Line

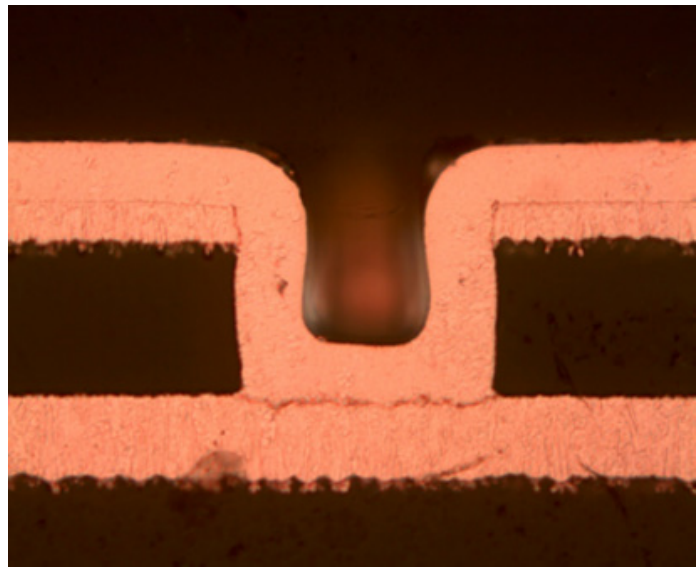
MacuSpec HT 300 is an advanced direct current acid copper system for thicker mid-range through hole metallization. With the benefits of pulse plating and none of the equipment upgrade costs, MacuSpec HT 300 is capable of plating copper with exceptional brightness, ductility and uniformity in through holes of up to 15:1 aspect ratio.

MacuSpec HT 300 is part of an advanced new portfolio of acid copper metallization systems that are easily analyzable by CVS and common analytical tools, making it excellent for bringing your plating operations under tighter statistical control while maintaining higher-than-ever production volumes. The deposit produced by MacuSpec HT 300 surpasses all IPC specifications required for through hole metallization in multi-layer board production.

Push back the need for pulse plating upgrades by one more generation with MacuSpec HT 300.

KEY FEATURES

- Enables higher technology board manufacturing requiring nothing other than swapping of chemical components
- Unsurpassed production capacity for DC plating for through holes of up to 15:1 ratio
- Excellent for through hole plating, conformal blind via plating, and pattern plating
- Easy bath analysis with CVS and common analytical tools
- Drop-in replacement, no expensive pulse rectification required
- Exceeds specifications required for multilayer including IPC TM-650 - Tensile >36,000 PSI, Elongation >12%

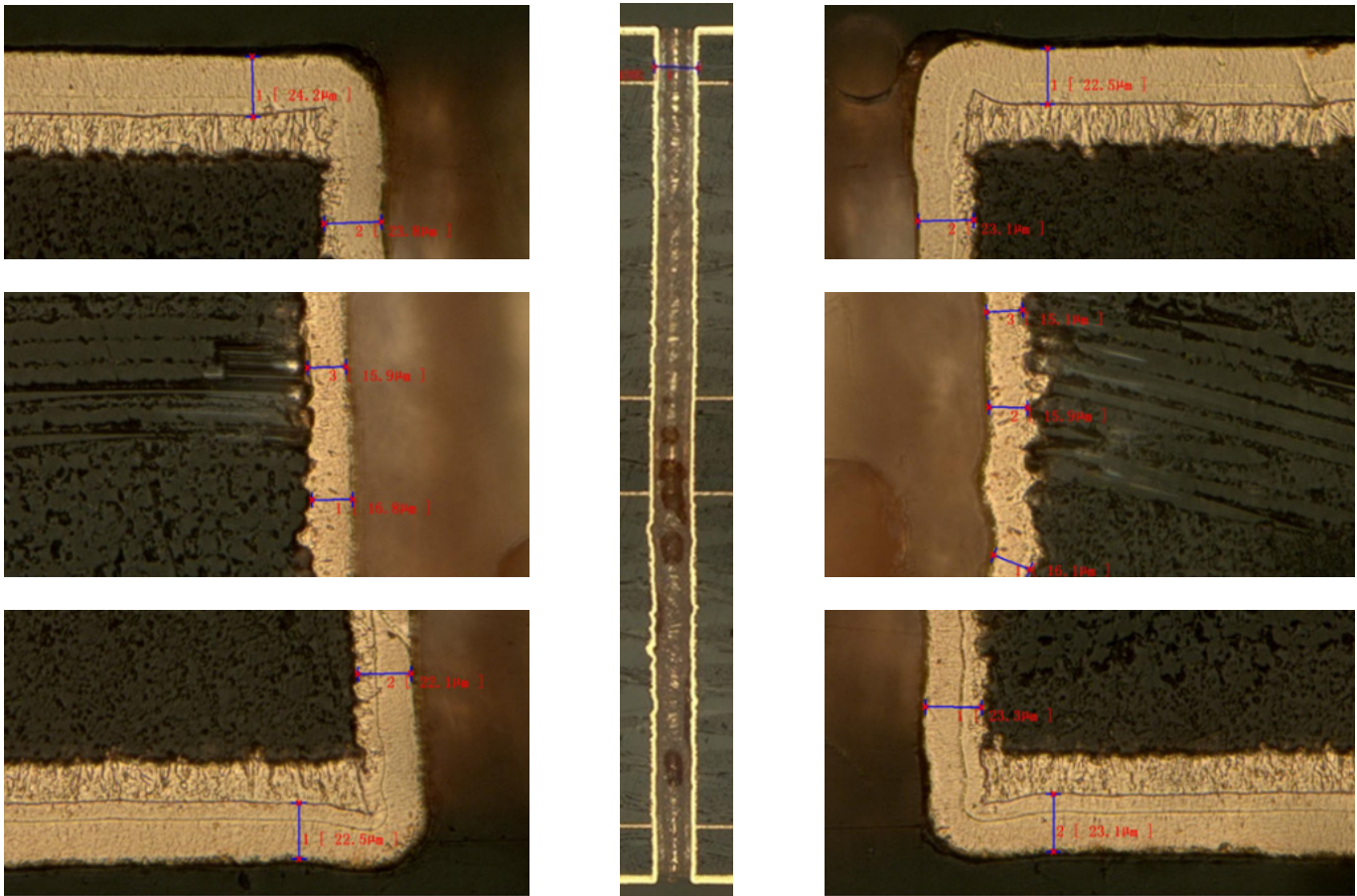


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Begin Supplying High Technology Markets with your Existing Plating Line

MacuSpec HT 300 is a next generation electrolytic copper metallization system designed for advanced electronics production. Precise analytical control with CVS and common analytical tools means that OEM quality boards can be produced from a simple direct current plating line. Make the switch today for higher production volume, quality, and technology capabilities from existing DC equipment.



Pictured above: 0.25 mm through hole in 3.5 mm board. The superior throwing power of the MacuSpec HT 300 system allows for metallization of through holes that would normally only be plated by pulse plating equipment.

